# Phase Synchronizing Clock Generator

# **Product Description**

P1P3800A is a Phase Synchronizing clock generator that generates four outputs from an input clock. Output frequency will be a divide by two of the input clock. The phase of the output clocks is selectable through four select signals S1, S2, S3 and S4. Refer to *Output Clock Selection Table*. The outputs will go 'low' when all the select signals are 'low'. The transition to a new state of the output will be 'glitch free' when the select inputs change state. A Power Down signal enables the device to be driven to a power save mode, when active. The device works over a supply voltage range of 3.8 V – 5.5 V. The device is available in a 12–Lead 3mmx3mm WQFN package and operates over -40°C to +85°C.

#### **Features**

- Input Clock Frequency:
  - 120 Hz 240 Hz (External Reference Clock)
- Output Clock Frequency:
  - 60 Hz 120 Hz
- 4 Clock Outputs
- 4 Two Level Controls to Select Sets of Clock Outputs
- Output Buffer Drive Strength: 8 mA
- Supply Voltage: 3.8 V 5.5 V
- Power Down for Power Save
- 12-Lead 3mmx3mm WQFN Package
- Operating Temperature Range: -40°C to +85°C
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

## **Application**

 P1P3800A can be used in applications where Phase Synchronization is needed.

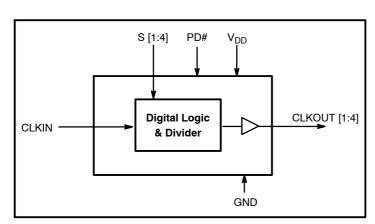


Figure 1. Block Diagram



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#### WQFN12 CASE 510AH

## MARKING DIAGRAM



A = Assembly Location

= Wafer Lot

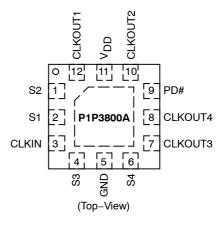
/ = Year

V = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

#### **PIN CONFIGURATION**



#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

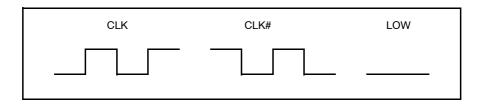
**Table 1. PIN DESCRIPTION** 

Pin#	Pin Name	Туре	Description
1	S2	I	Output clock select. Refer Output Clock selection table. Has NO default state
2	S1	I	Output clock select. Refer Output Clock selection table. Has NO default state.
3	CLKIN	I	External Reference Clock Input
4	S3	I	Output clock select. Refer Output Clock selection table. Has NO default state.
5	GND	Р	Ground to entire chip
6	S4	I	Output clock select. Refer Output Clock selection table. Has NO default state.
7	CLKOUT3	0	Buffered clock output. Refer CLKOUT Diagram
8	CLKOUT4	0	Buffered clock output. Refer CLKOUT Diagram
9	PD#	I	Power Down. Powers down the entire chip when pulled LOW. CLKOUT [1:4] will be LOW when power down is enabled. Has NO default state.
10	CLKOUT2	0	Buffered clock output. Refer CLKOUT Diagram
11	V <sub>DD</sub>	Р	Supply Voltage
12	CLKOUT1	0	Buffered clock output. Refer CLKOUT Diagram

# **Table 2. OUTPUT CLOCK SELECTION TABLE**

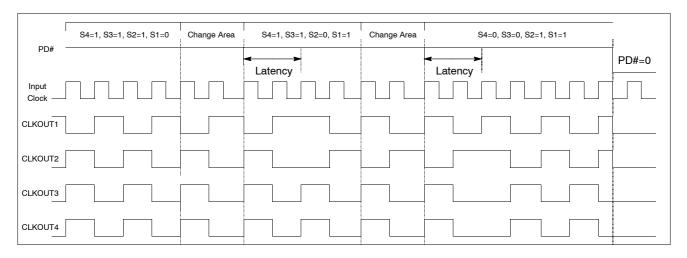
S4	S3	S2	S1	CLKOUT4	CLKOUT3	CLKOUT2	CLKOUT1
0	0	0	0	Low	Low	Low	Low
0	0	0	1	CLK#	CLK#	CLK#	CLK
0	0	1	0	CLK#	CLK#	CLK	CLK#
0	0	1	1	CLK#	CLK#	CLK	CLK
0	1	0	0	CLK#	CLK	CLK#	CLK#
0	1	0	1	CLK#	CLK	CLK#	CLK
0	1	1	0	CLK#	CLK	CLK	CLK#
0	1	1	1	CLK#	CLK	CLK	CLK
1	0	0	0	CLK	CLK#	CLK#	CLK#
1	0	0	1	CLK	CLK#	CLK#	CLK
1	0	1	0	CLK	CLK#	CLK	CLK#
1	0	1	1	CLK	CLK#	CLK	CLK
1	1	0	0	CLK	CLK	CLK#	CLK#
1	1	0	1	CLK	CLK	CLK#	CLK
1	1	1	0	CLK	CLK	CLK	CLK#
1	1	1	1	CLK	CLK	CLK	CLK

# **CLKOUT Diagram**



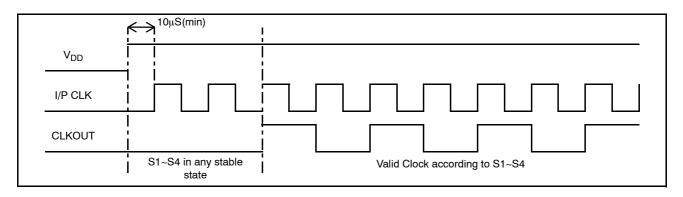
# **TIMING Diagram For Glitch Free Operation (For Reference)**

(Transition of outputs from any state to any other state)



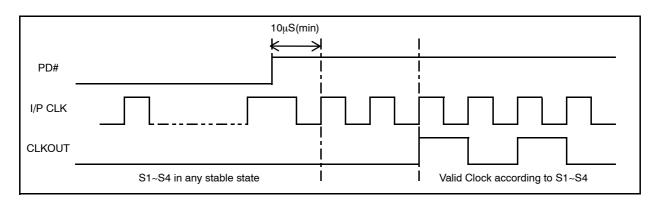
Note: Transition to new state will happen after a latency of one output clock cycle after completing the present output clock cycle Transition to new state will happen after a latency of up to 3 input clock cycles excluding the input cycle where the transition has occured.

# **Power Up**



Note: Transition to new state will happen after a latency of up to 2 input clock cycles excluding the input cycle where the transition has occured.

# PD# Operation



Note: Transition to new state will happen after a latency of up to 2 input clock cycles excluding the input cycle where the transition has occured.

**Table 3. OPERATING CONDITIONS** 

Symbol	Parameter	Min	Max	Unit
$V_{DD}$	Supply Voltage	3.8	5.5	V
T <sub>A</sub>	Operating Temperature	-40	+85	°C
C <sub>L</sub>	Load Capacitance		15	pF
C <sub>IN</sub>	Input Capacitance		7.0	pF

#### **Table 4. ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Rating	Unit
V <sub>DD</sub>	Voltage on V <sub>DD</sub> pin with respect to Ground	-0.5 to +7.0	V
V <sub>IN</sub>	Voltage on any input pin with respect to Ground	-0.5 to +4.0	V
T <sub>STG</sub>	Storage Temperature	-65 to +125	°C
T <sub>s</sub>	Max. Soldering Temperature (10 sec)	260	°C
TJ	Junction Temperature	150	°C
$T_DV$	Static Discharge Voltage (As per JEDEC STD22-A114-B)	2.0	kV

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### **Table 5. DC ELECTRICAL CHARACTERISTICS**

Symbol	Parameter	Min	Тур	Max	Unit	
V <sub>DD</sub>	Operating Voltage		3.8	5.0	5.5	V
V <sub>IL</sub>	Input Low Voltage (Note 1)		GND - 0.3		0.8	V
V <sub>IH</sub>	Input High Voltage (Note 1)		1.6		3.0	V
I <sub>IL</sub>	Input Low Current				10	μΑ
I <sub>IH</sub>	Input High Current				10	μΑ
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 8 mA			0.4	V
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = -8 mA	V <sub>DD</sub> - 0.6*			V
I <sub>CC</sub>	Power Down Current (PD# pulled to GND)			1.0		μΑ
I <sub>DD</sub>	**Dynamic Supply Current, PD# = 5.5 V; S[1:4] = 5.5 V/GND; CLKIN Swing = 0 to 5.5 V; $V_{DD}$ = 5.5 V				1.8	mA
	Dynamic Supply Current, PD# = 3 V; S[1:4] = 3 V/GND; CLKIN Swing = 0 to 3.0 V				3.0	
	Dynamic Supply Current, PD# = 3 V; S[1:4] = 1.6 V; CLKIN Swing = 0 to 1.6 V				4.0	
	Dynamic Supply Current, PD# = S[1:4] = 1.6 V; CLKIN Swing = 0 to 1.6 V				5.0	

<sup>\*</sup>For V<sub>DD</sub> = 5 V, V<sub>OH</sub> = V<sub>DD</sub> - 0.4 V. \*\*Indicative value, not a recommended operating condition.

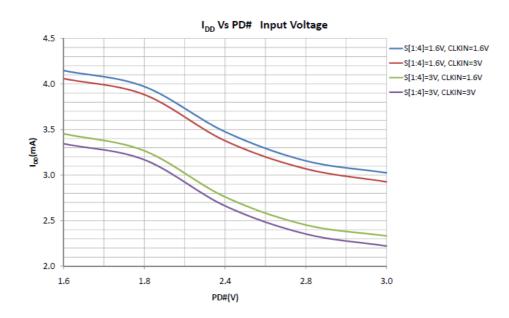
<sup>1.</sup> Parameter is guaranteed by design and characterization. Not tested in production.

**Table 6. AC ELECTRICAL CHARACTERISTICS** 

Symbol	Parameter	Min	Тур	Max	Unit
CLKIN	Input Clock Frequency	120		240	Hz
CLKOUT	Output Clock Frequency	60		120	Hz
t <sub>LH</sub> , t <sub>HL</sub>	Output Rise / Fall time (Measured from 20% to 80%) (Notes 1, 2)			10	μs
t <sub>LH</sub> , t <sub>HL</sub>	Input Rise / Fall time (Measured from 20% to 80%)			50	μs
<sup>†</sup> DOUT	Output Duty Cycle (Measured at V <sub>DD</sub> /2) (Notes 1, 2)	49	50	51	%
t <sub>DIN</sub>	Input Duty Cycle	49	50	51	%
t <sub>su</sub>	Set up time for control signals, S[1:4], PD# to input clock rising edge (Note 1)	60			μs
t <sub>h</sub>	Hold up time for control signals, S[1:4], PD# to input clock rising edge (Note 1)	60			μs
t <sub>skew</sub>	Output-Output Clock Skew (Note 1)			10	μs

<sup>2.</sup> All parameters are specified with 15 pF loaded output.

# Typical I<sub>DD</sub> Vs PD# Input Voltage Plot

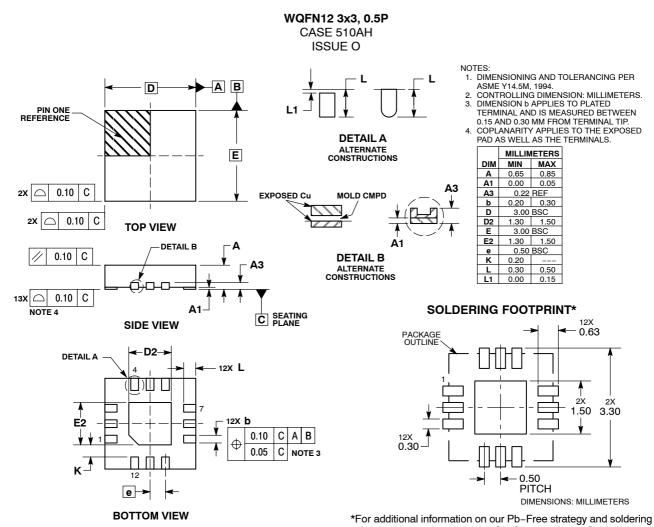


#### **ORDERING INFORMATION**

Part Number	Package	Shipping <sup>†</sup>	
P1P3800AG12CRTWG	12 pin (3 mm x 3 mm) WQFN	3000 / Tape & Reel	

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS



details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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